TOSHIBA BI-CMOS INTEGRATED CIRCUIT SILICON MONOLITHIC

# TB62706BN,TB62706BF

#### 16BIT SHIFT REGISTER, LATCHES & CONSTANT CURRENT DRIVERS

The TB62706BN, TB62706BF is specifically designed for LED and LED DISPLAY constant current drivers.

This constant current output circuits is able to set up external resistor (IOUT =  $5\sim90$  mA). (Note)

This  $I_C$  is monolithic integrated circuit designed to be used together with Bi-CMOS process.

The devices consist of 16bit shift register, latch, AND–GATE and Constant Current Drivers.

#### **FEATURES**

• Constant Current Output : Can set up all output current

with one resister for 5 to 90

mA.

• Maximum Clock Frequency: fclk = 15 (MHz) (Cascade

Connected Operate,  $T_{opr} =$ 

25°C)

• 5 V C-MOS Compatible Input

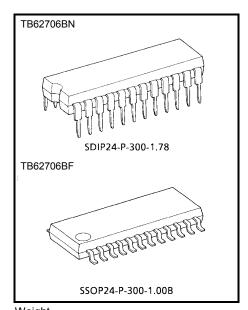
Package: SDIP24-P-300-1.78~1.778mmPitch~ (TB62706BN)

SSOP24-P-300-1.00B~1.0mmPitch~ (TB62706BF)

Constant Output Current Matchong:

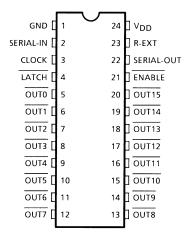
OUTPUT-GND VOLTAGE	CURRENT MATCHING	OUTPUT CURRENT	
≥ 0.4 V	±6.0%	5~40 mA	
≥ 0.7 V	±6.0%	5~90 mA	(Note)

Note: TB62706BF can be used under limited  $P_D$ ( $P_D \le 1.04 \text{ W}$ , with PCB)

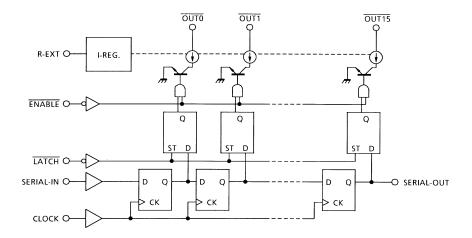


Weight SDIP24-P-300-1.78: 1.22 g (typ.) SSOP24-P-300-1.00B: 0.32 g (typ.)

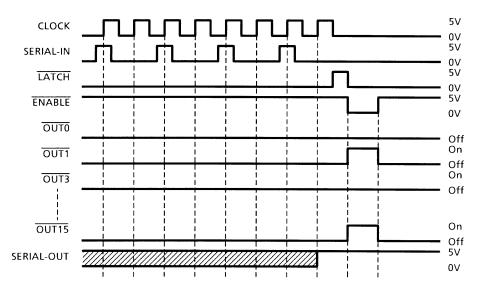
### **PIN CONNECTION (Top view)**



#### **BLOCK DIAGRAM**



#### **TIMING DIAGRAM**



Note: Latches are level sensitive, not rising edges sensitive and not syncronus CLOCK.

Input of LATCH-terminal to H Level, data passes latches, and input to L level, data hold latches.

Input of ENABLE-terminal to H level, all output (OUT0~15) do off.

#### **TERMINAL DISCRIPTION**

PIN No.	PIN NAME	FUNCTION
1	GND	GND terminal for control logic.
2	SERIAL-IN	Input terminal of a serial-data for shift-register.
3	CLOCK	Input terminal of a clock for data shift to up-edge.
4	LATCH	Input terminal of a data strobe. Latches passes data with "H" level input of LATCH -terminal, and hold data with "L" level input.
5~20	OUT0 ~15	Output terminals.
21	ENABLE	Input terminal of output enable. All outputs (OUT0~15) do off with "H" level input of ENABLE –terminal, and do on with "L" level input.
22	SERIAL-OUT	Output terminal of a serial-data for next SERIAL-IN terminal.
23	R-EXT	Input terminal of connects with a resister for to set up all output current.
24	$V_{DD}$	5 V Supply voltage terminal.

#### **TRUTH TABLE**

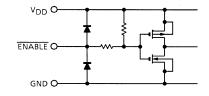
CLOCK	LATCH	ENABLE	SERIAL-IN	OUTO ··· OUT7 ··· OUT15	SERIAL-OUT
UP	Н	L	D <sub>n</sub>	$D_n \cdots D_{n-7} \cdots D_{n-15}$	D <sub>n-15</sub>
UP	L	L	D <sub>n+1</sub>	No change	D <sub>n-14</sub>
UP	Н	L	D <sub>n+2</sub>	$D_{n+2} \cdots D_{n-5} \cdots D_{n-13}$	D <sub>n-13</sub>
DOWN	Х	L	D <sub>n+3</sub>	$D_{n+2} \cdots D_{n-5} \cdots D_{n-13}$	D <sub>n-13</sub>
DOWN	Х	Н	D <sub>n+3</sub>	Off	D <sub>n-13</sub>

Note:  $\overline{OUT0 \sim 15}$  = on in case of  $D_n$  = H level and  $\overline{OUT0 \sim 15}$  = off in case of  $D_n$  = L level.

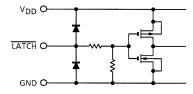
A resistor is connected with R-EXT and GND accompanied with outside, and it is necessary that a correct power supply voltage is supplied.

### **EQUIVALENT CIRCUIT OF INPUTS AND OUTPUTS**

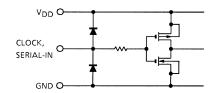
### 1. **ENABLE** terminal



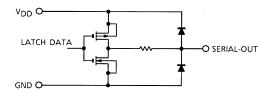
### 2. **LATCH** terminal



### 3. CLOCK, SERIAL-IN terminal



#### 4. SERIAL-OUT terminal



### ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT	
Supply Voltage	$V_{DD}$	0~7.0	V	
Input Voltage	V <sub>IN</sub>	-0.4~V <sub>DD</sub> + 0.4	V	
Output Current	lout	90	mA	
Output Voltage	V <sub>OUT</sub>	-0.5~17.0	V	
Clock Frequency	f <sub>CK</sub> 15		MHz	
GND Terminal Current	I <sub>GND</sub>	1440	mA	
Power Dissipation	PD	1.78 (BN-type : ON PCB, Ta = 25°C )	w	
Power Dissipation	FD	1.00 (BF-type : ON PCB, Ta = 25°C )	T VV	
Tharmal Resistance	D	BN : 70 (BN-type : ON PCB)	°C/W	
mamai Resistance	R <sub>th (j−a)</sub>	BF : 120 (BF-type : ON PCB)	]	
Operating Temperature	T <sub>opr</sub> -40~85		°C	
Storage Temperature	T <sub>stg</sub>	-55~150	°C	

Note: BN-type :Ambient temperature delated above 25°C in the proportion of 14.2 mW / °C BF-type : Ambient temperature delated above 25°C in the proportion of 8.3 mW / °C

### RECOMMENDED OPERATING CONDITION (Ta = -40~85°C unless otherwise noted)

CHARACTERISTIC	SYMBOL	CONDITION	MIN	TYP.	MAX	UNIT
Supply Voltage	$V_{DD}$	_	4.5	5.0	5.5	V
Output Voltage	V <sub>OUT</sub>	_	_	_	15.0	V
	IO	OUTn, DC 1 circuit	5	_	88	
Output Current	I <sub>OH</sub>	SERIAL-OUT	_	_	1.0	mA
	I <sub>OL</sub>	SERIAL-OUT	_	_	-1.0	
Input Voltage	V <sub>IH</sub>	_	0.7 V <sub>DD</sub>	_	V <sub>DD</sub> +0.3	٧
mput voltage	V <sub>IL</sub>	_	-0.3	_	0.3 V <sub>DD</sub>	
LATCH Pulse Width	tw LAT		100	_	_	ns
CLOCK Pulse Width	t <sub>w CLK</sub>		50	_	_	ns
ENABLE Pulse Width	t <sub>w</sub> <del>EN</del>		4500	_	_	ns
Set-Up Time for DATA	t <sub>setup (D)</sub>	V <sub>DD</sub> = 4.5~5.5 V	60	_	_	ns
Hold Time for DATA	t <sub>hold (D)</sub>		20	_	_	ns
Set-Up Time for LATCH	t <sub>setup (L)</sub>		100	_	_	ns
Hold Time for LATCH	t <sub>hold (L)</sub>		60	_	_	ns
Clock Frequency	fclk	Cascade operation	_	_	10.0	MHz
Power Dissipation	PD	Ta = 85°C (BN-type)	_	_	0.92	W
1 Ower Dissipation	טיי	Ta = 85°C (BF-type)	_	_	0.50	VV

## ELECTRICAL CHARACTERISTICS (V<sub>DD</sub> = 5.0 V, Ta = 25°C unless otherwise noted)

CHARACTERISTIC		SYMBOL	TEST CIR- CUIT	CON	DITION	MIN	TYP.	MAX	UNIT	
Input Voltage	"H" Level	V <sub>IH</sub>	_	Ta = −40~85°C		0.7 V <sub>DD</sub>	_	V <sub>DD</sub>	V	
input voltage	"L" Level	V <sub>IL</sub>	_	Ta = −40~85°C		GND	_	0.3 V <sub>DD</sub>		
Output Leakage Cu	urrent	I <sub>OH</sub>	_	V <sub>OH</sub> = 15.0 V			_	10	μA	
Output Voltage	SERIAL-OUT	V <sub>OL</sub>	_	I <sub>OL</sub> = 1.0 mA		_	_	0.4	V	
Output Voltage	SERIAL-001	V <sub>OH</sub>	_	I <sub>OH</sub> = −1.0 mA		4.6	_	_	v	
0		I <sub>OL1</sub>	_	V <sub>CE</sub> = 0.7 V	R <sub>EXT</sub> = 470 Ω	34.1	40.0	45.9	^	
Output Current 1		I <sub>OL2</sub>	_	V <sub>CE</sub> = 0.4 V	(Include current matching)	33.7	39.5	45.3	mA	
	Current Skew	Δ l <sub>OL1</sub>	_	I <sub>O</sub> = 40 mA, V <sub>CE</sub> = 0.4 V	R <sub>EXT</sub> = 470 Ω	_	±1.5	±6.0	%	
0		I <sub>OL3</sub>	_	V <sub>CE</sub> = 1.0 V	R <sub>EXT</sub> = 250 Ω	64.2	75.5	86.8	mA	
Output Current 2		I <sub>OL4</sub>	_	V <sub>CE</sub> = 0.7 V	(Include current matching)	63.8	75.0	86.2		
	Current Skew	Δ l <sub>OL2</sub>	_	I <sub>O</sub> = 75 mA, V <sub>CE</sub> = 0.7 V	R <sub>EXT</sub> = 250 Ω	_	±1.5	±6.0	%	
Supply Voltage Re	gulation	% / V <sub>DD</sub>	_	R <sub>EXT</sub> = 470 Ω, Ta = -40~85°C		_	1.5	5.0	% / V	
Pull-Up Resistor		R <sub>IN</sub> (up)	_	_		150	300	600	Ω	
Pull-Down Resisto	r	R <sub>IN (down)</sub>	_	_		100	200	400	Ω	
	"OFF"	I <sub>DD</sub> (off) 1	_	$\frac{R_{EXT} = OPEN,}{OUT0 \sim 15} = 0$	off	_	0.6	1.2		
Supply Current		I <sub>DD (off) 2</sub>	_	R <sub>EXT</sub> = 470 Ω,	<u>OUT0 ~15</u> = off	3.5	5.8	8.0	mA	
		I <sub>DD</sub> (off) 3	_	R <sub>EXT</sub> = 250 Ω,	OUT0 ~15 = off	6.5	10.7	15.0		
	"ON"	I <sub>DD</sub> (on) 1	_	R <sub>EXT</sub> = 470 Ω,	<u>OUT0 ~15</u> = on	10.0	16.0	22.0		
	ON	I <sub>DD</sub> (on) 2	_	R <sub>EXT</sub> = 250 Ω,	OUT0 ~15 = on	18.0	28.3	38.5		

5 2006-06-14

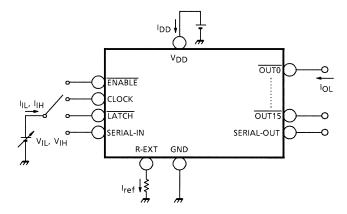
## SWITCHING CHARACTERISTICS (Ta = 25°C unless otherwise noted)

CHARA	ACTERISTIC	SYMBOL	TEST CIR- CUIT	CONDITION	MIN	TYP.	MAX	UNIT		
	CLK- OUTn				_	1200	1500	- ns		
Propagation Delay Time	LATCH - OUTn	<b>+</b>			_	1200	1500			
("L" to "H")	ENABLE - OUTn	t <sub>pLH</sub>			_	1200	1500			
	CLK-SOUT				15	30	70			
	CLK- OUTn				_	700	1000			
Propagation Delay Time	LATCH - OUTn	<b>4</b>		$V_{DD} = 5.0 \text{ V}$ $V_{CE} = 0.4 \text{ V}$ $V_{IH} = V_{DD}$ $V_{IL} = \text{GND}$ $R_{EXT} = 470 \Omega$ $V_{L} = 3.0 \text{ V}$ $R_{L} = 65 \Omega$ $C_{L} = 10.5 \text{ pF}$	_	700	1000	- ns		
("H" to "L")	ENABLE - OUTn	t <sub>pHL</sub>			_	700	1000			
	CLK-SOUT				15	30	70			
Pulse Width	CLK	t <sub>w CLK</sub>	_		_	20	30	ns		
ruise widiii	LATCH	tw <del>LAT</del>	_		_	10	25	ns		
Set-up Time	L-H	t <sub>setup (L)</sub>			_	25	50	ns		
Set up Tille	H-L	t <sub>setup (C)</sub>			]	ο 10.5 μι	_	25	50	ns
Hold Time	L-H	t <sub>hold</sub> (L)			_	0	15	ns		
Tiola Tille	H-L	t <sub>hold (C)</sub>		1 -		_	0	15	ns	
Maximum CLOCK Rise Time		t <sub>r</sub>				_	10	μs		
Maximum CLOCK Fall Time		t <sub>f</sub>			_	_	10	μs		
Output Rise Time		t <sub>or</sub>	_		150	300	600	ns		
Output Fall Time		t <sub>of</sub>	_		150	300	600	ns		

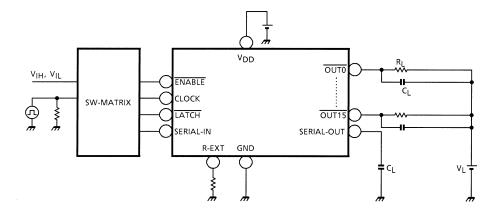
6 2006-06-14

### **TEST CIRCUIT**

#### **DC** characteristic



### **AC** characteristic

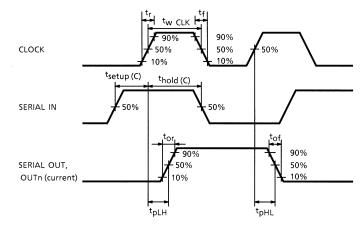


### **PRECAUTIONS for USING**

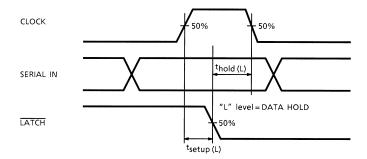
Utmost care is necessary in the design of the output line,  $V_{CC}$  ( $V_{DD}$ ) and GND line since IC may be destroyed due to short–circuit between outputs, air contamination fault, or fault by improper grounding.

### **TIMING WAVEFORM**

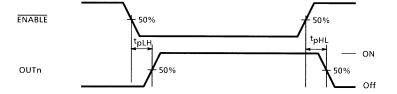
### 1. CLOCK-SERIAL OUT, OUTn

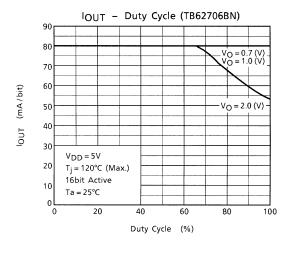


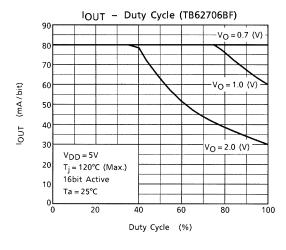
### 2. CLOCK-LATCH

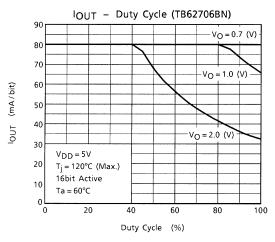


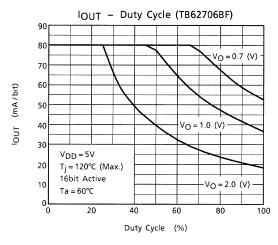
### 3. ENABLE -OUTn

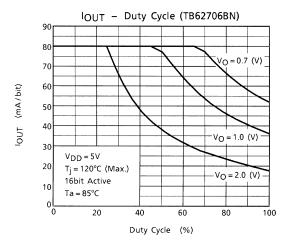


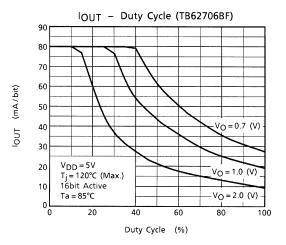


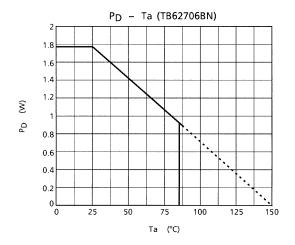


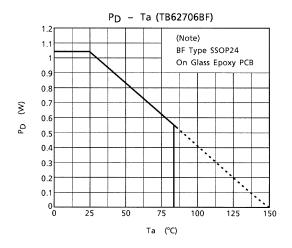












### LED DRIVER TB6270X SERIES APPICATION NOTE

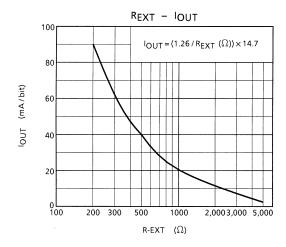


Fig.1

#### [1] Output current (IOUT)

IOUT is set by the enternal resistor (R-EXT) as shown in Fig.1.

#### [2] Total supply voltage (VLED)

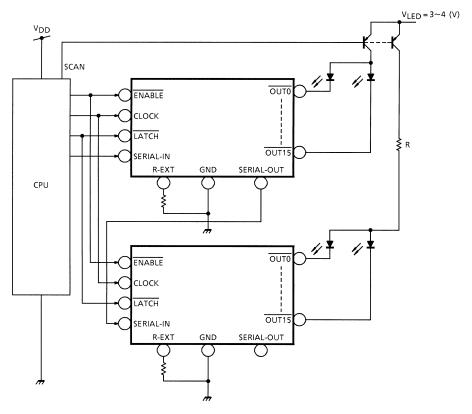
This device can operate 0.4~0.7V (VO).

When a higher voltage is input to the device, the excess voltage is consumed inside the device, that leads to power dissipation.

In order to minimize power dissipation and loss, we would like to recommend to set the total supply voltage as shown below.

 $V_{\rm LED} \ ({\rm total \ supply \ voltage}) = V_{\rm CE} \ ({\rm Tr} \ V_{\rm sat}) + V_{\rm f} \ ({\rm LED \ Forward \ voltage}) + V_{\rm O} \ ({\rm IC \ supply \ voltage})$ 

When the total supply is too high considering the power dissipation of this device, an additional R can decrease the supply voltage (Vo).



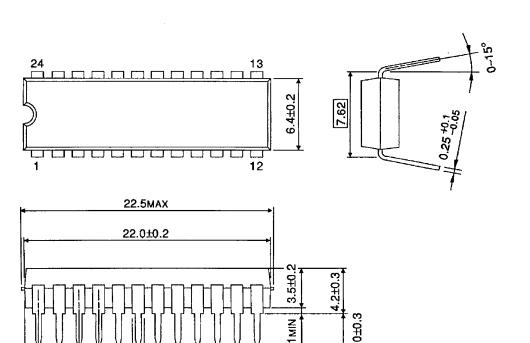
#### [3] Pattern layout

This device owns only one ground pin that means signal ground pin and power ground pin are common. If ground pattern layout contains large inductance and impedance, and the voltage between ground and LATCH, CLOCK terminals exceeds 2.5 V by switching noise in operation, this device may miss-operate. So we would lile you to pay attention to pattern layout to minimize inductance.

Unit: mm

### **Package Dimensions**

SDIP24-P-300-1.78



0.46±0.1 0.18 M

1.0±0.1

1.778

Weight: 1.22 g (typ.)

1.221TYP

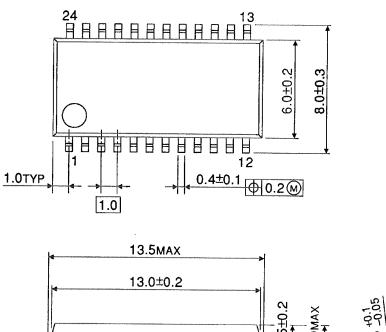
Unit: mm

(300mil)

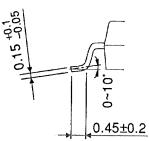
7.62

### **Package Dimensions**

SSOP24-P-300-1.00B



**2** 0.15



Weight: 0.32 g (typ.)

0.1+0.1

#### **Notes on Contents**

### 1. Block Diagrams

Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

#### 2. Equivalent Circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

#### 3. Timing Charts

Timing charts may be simplified for explanatory purposes.

### 4. Application Circuits

The application circuits shown in this document are provided for reference purposes only.

Thorough evaluation is required, especially at the mass production design stage.

To shiba does not grant any license to any industrial property rights by providing these examples of application circuits.

#### 5. Test Circuits

Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.

### **IC Usage Considerations**

#### Notes on Handling of ICs

- (1) The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.
  Exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.
- (2) Use an appropriate power supply fuse to ensure that a large current does not continuously flow in case of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead smoke or ignition. To minimize the effects of the flow of a large current in case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.
- (3) If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. IC breakdown may cause injury, smoke or ignition.
  Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.
- (4) Do not insert devices in the wrong orientation or incorrectly. Make sure that the positive and negative terminals of power supplies are connected properly. Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion. In addition, do not use any device that is applied the current with inserting in the wrong orientation or incorrectly even just one time.
- (5) Carefully select external components (such as inputs and negative feedback capacitors) and load components (such as speakers), for example, power amp and regulator.

  If there is a large amount of leakage current such as input or negative feedback condenser, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure can cause smoke or ignition. (The over current can cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied Load (BTL) connection type IC that inputs output DC voltage to a speaker directly.

#### Points to Remember on Handling of ICs

(1) Heat Radiation Design

In using an IC with large current flow such as power amp, regulator or driver, please design the device so that heat is appropriately radiated, not to exceed the specified junction temperature (Tj) at any time and condition. These ICs generate heat even during normal use. An inadequate IC heat radiation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into considerate the effect of IC heat radiation with peripheral components.

(2) Back-EMF

When a motor rotates in the reverse direction, stops or slows down abruptly, a current flow back to the motor's power supply due to the effect of back-EMF. If the current sink capability of the power supply is small, the device's motor power supply and output pins might be exposed to conditions beyond maximum ratings. To avoid this problem, take the effect of back-EMF into consideration in system design.

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16

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